Product Change Notification: MFOL-24BTDL410

Date:

30-Jul-2025

Product Category:

Analog to Digital Converters

Notification Subject:

CCB 7720 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and 558-2C31 as a new die attach material for MCP3914A1T-E/MVVAO, MCP3914A1-E/MV, MCP3914A1T-E/MV, MCP3913A1-E/MV, MCP3913A1T-E/MV, MCP3913A1T-E/MVVAO, MCP3914BA1T-E/MV, MCP3913BA1-E/MV, MCP3913BA1T-E/MV, and MCP3914BA1-E/MV catalog part numbers (CPN) available in 40L UQFN (5x5x0.5mm) package at NSEB assembly site.

Affected CPNs:

MFOL-24BTDL410_Affected_CPN_07302025.pdf
MFOL-24BTDL410_Affected_CPN_07302025.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and 558-2C31 as a new die attach material for MCP3914A1T-E/MVVAO, MCP3914A1-E/MV, MCP3914A1T-E/MV, MCP3913A1-E/MV, MCP3913A1T-E/MV, MCP3913A1T-E/MVVAO, MCP3914BA1T-E/MV, MCP3913BA1-E/MV, MCP3913BA1T-E/MV, and MCP3914BA1-E/MV catalog part numbers (CPN) available in 40L UQFN (5x5x0.5mm) package at NSEB assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	UTAC Thai Limited (UTL-1) (NSEB)	UTAC Thai Limited (UTL-1) (NSEB)

Wire Material	Au	CuPdAu
Die Attach Material	8600	558-2C31
Molding Compound Material	G700LTD	G700LTD
Lead-Frame Material	EFTEC-64T	EFTEC-64T
Lead-Frame Lead lock	U-groove and Dimple	Dimple
Lead-Frame Design	See Pre and Post change for change for comparison.	
DAP Surface Prep	Ag ring and Ag on lead & Ag on lead only (Cu-RT)	Ag on lead only (Cu-RT)

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new wire material and 558-2C31 as a new die attach material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: January 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	July 2025					>	**January 2026**				
Work Week	27	28	29	30	31		01	02	03	04	05
Initial PCN Issue Date					X						
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: July 30, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-24BTDL410 Pre and Post Change_Summary.pdf
PCN_MFOL-24BTDL410_Qual Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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